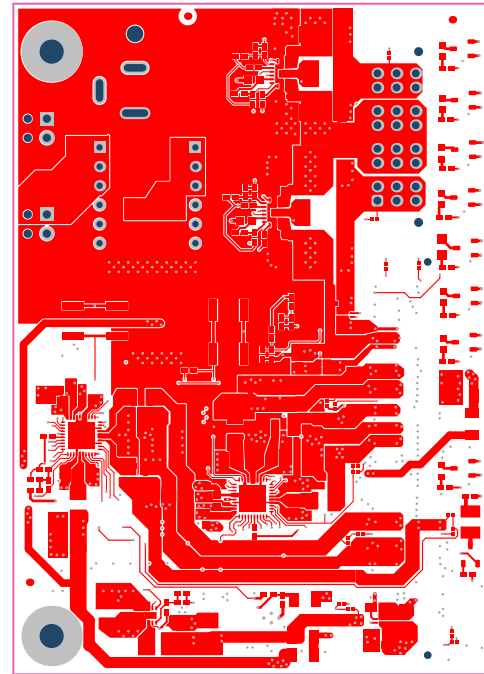


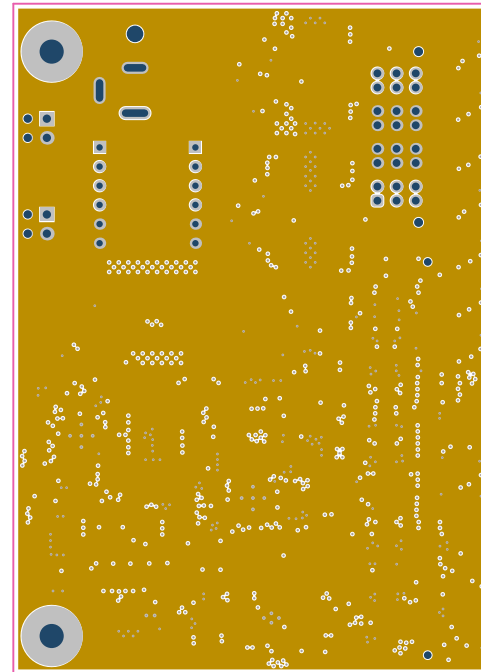
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01480		
PLOT NAME = Top Overlay	GENERATED : 12/7/2017 11:06:25 AM	TEXAS INSTRUMENTS	



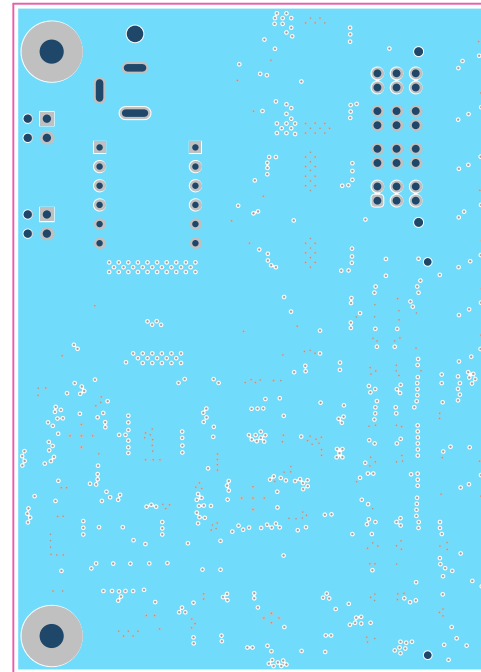
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01480		
PLOT NAME = Top Solder Mask	GENERATED : 12/7/2017 11:06:27 AM	TEXAS INSTRUMENTS	



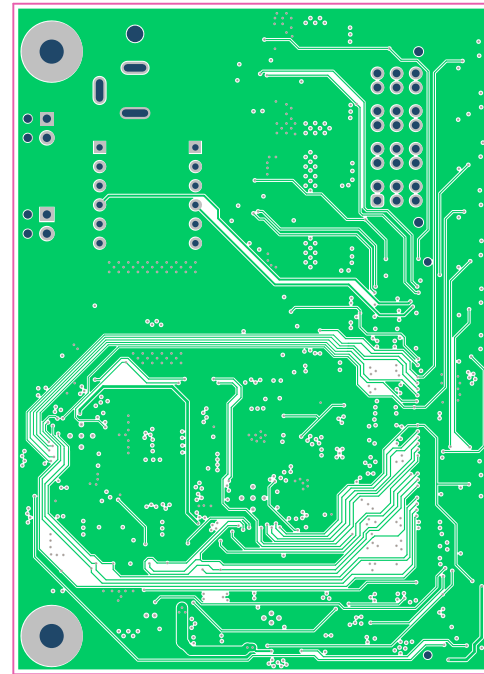
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01480		
PLOT NAME = Top Layer	GENERATED : 12/7/2017 11:06:28 AM	TEXAS INSTRUMENTS	



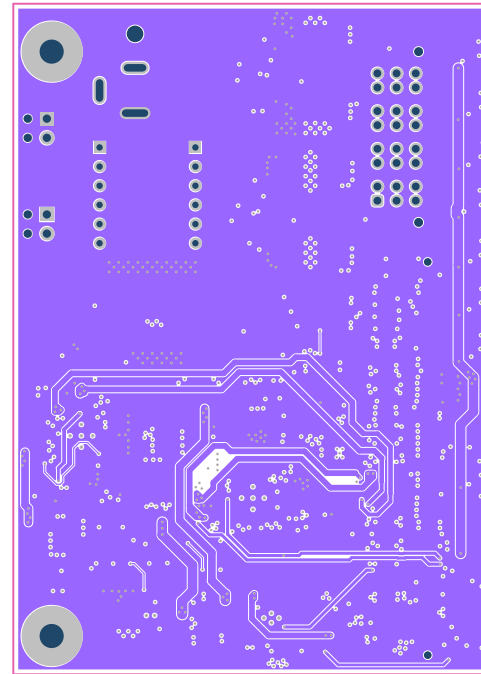
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01480		
PLOT NAME = Signal Layer 1	GENERATED : 12/7/2017 11:06:30 AM	TEXAS INSTRUMENTS	



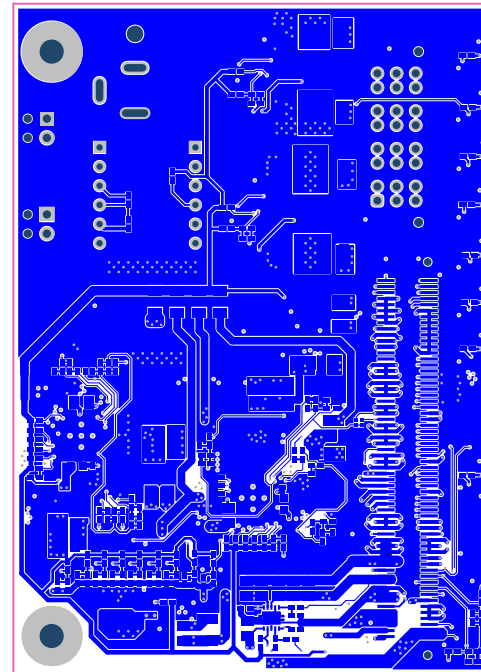
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01480		
PLOT NAME = Signal Layer 2	GENERATED : 12/7/2017 11:06:31 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01480		
PLOT NAME = Signal Layer 3	GENERATED : 12/7/2017 11:06:33 AM	TEXAS INSTRUMENTS	

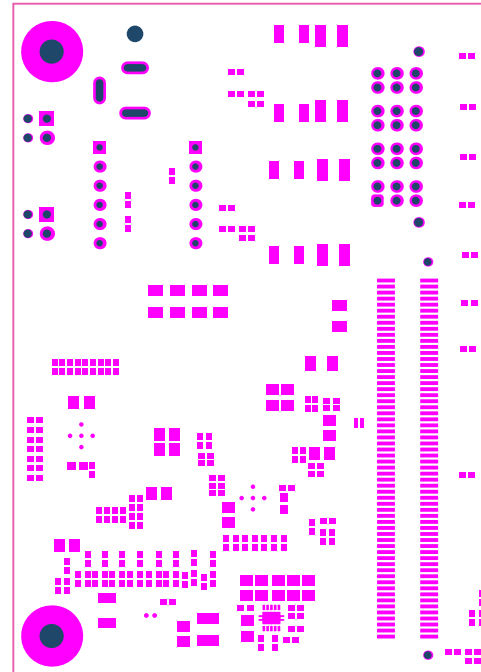


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01480		
PLOT NAME = Signal Layer 4	GENERATED : 12/7/2017 11:06:35 AM	TEXAS INSTRUMENTS	

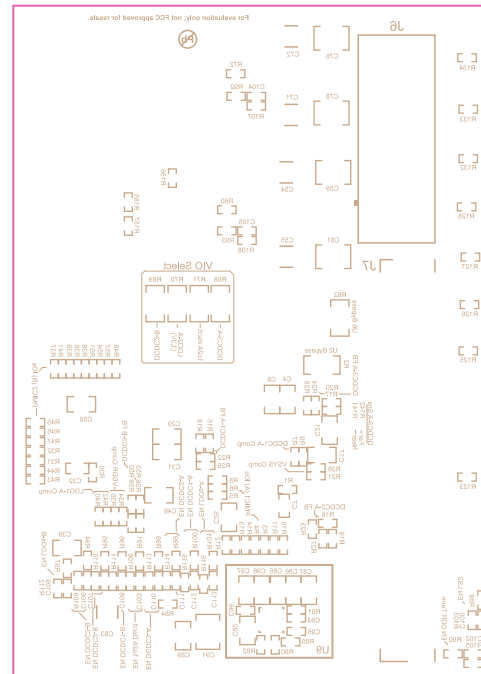


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01480		
PLOT NAME = Bottom Layer	GENERATED : 12/7/2017 11:06:36 AM	TEXAS INSTRUMENTS	

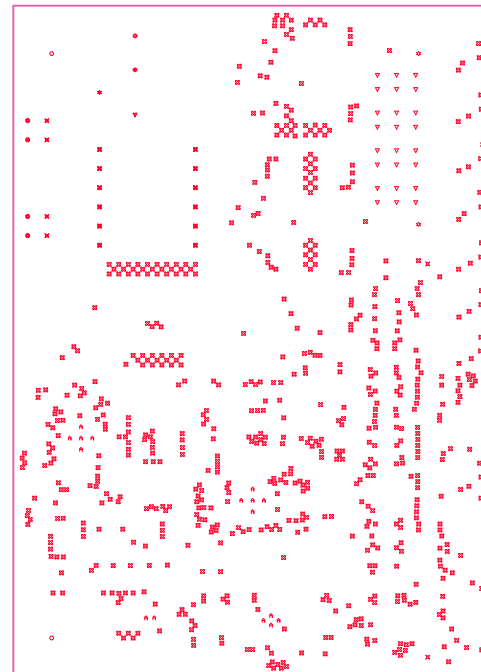




ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01480		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/7/2017 11:06:38 AM	TEXAS INSTRUMENTS	



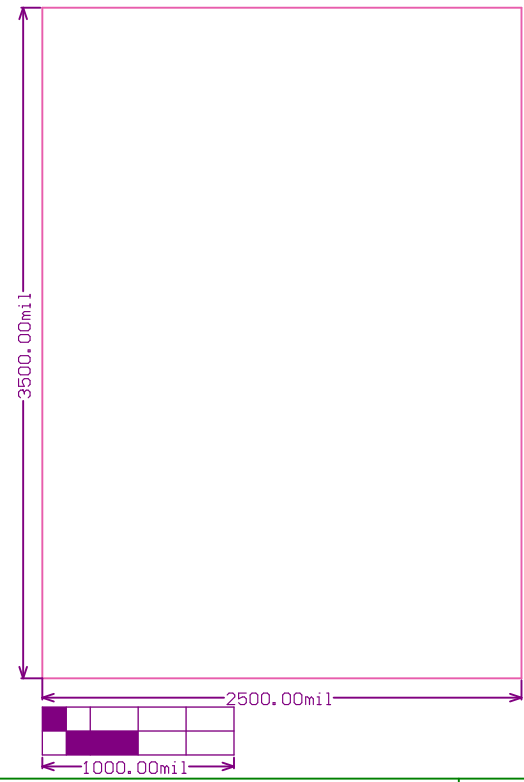
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01480		
PLOT NAME = Bottom Overlay	GENERATED : 12/7/2017 11:06:39 AM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Tolerance (+)
⊠	676	7.90mil (0.201mm)	PTH	Round	Top Layer - Bottom Layer	Via	
▽	24	40.95mil (1.040mm)	PTH	Round	Top Layer - Bottom Layer	Pad	
△	16	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Via	
⊠	12	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	Pad	
⊠	4	43.31mil (1.100mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	
⊠	4	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	Pad	
⊠	2	39.37mil (1.000mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	
⊠	2	40.16mil (1.020mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	
⊠	2	46.85mil (1.190mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	
○	2	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	Pad	
▽	1	39.37mil (1.000mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	
⊠	1	86.61mil (2.200mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	
746 Total							

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01480		
PLOT NAME = Drill Drawing	GENERATED : 12/7/2017	11:06:41 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01480	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01480		
PLOT NAME = Board Dimensions	GENERATED : 12/7/2017 11:06:45 AM	TEXAS INSTRUMENTS	

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